

## KA-8080/2 SERIES



**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

### Features

- High efficient lightsource.
- Designed for high current operation.
- Low thermal resistance.
- Encapsulation : Silicone resin.
- Compatible with IR-reflow processes.
- ESD protection .
- Package : 500pcs / reel.
- RoHS compliant.



### Applications

- Substitution of micro incandescent lamps.
- Portable light source.
- Signal and symbol luminaire for orientation.
- Marker lights (e.g. steps, exit ways, etc).
- Decorative and entertainment lighting.
- Commercial and residential lighting.
- Emergency-vehicle lighting.

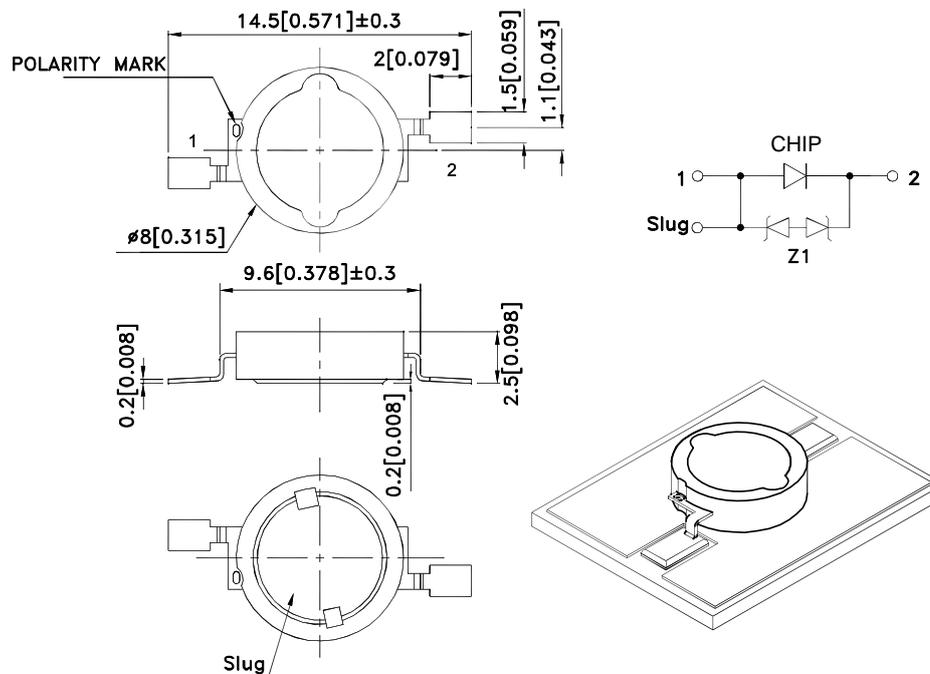
### Application Note

Static electricity and surge damage the LEDs.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

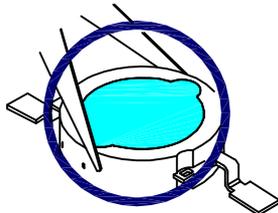


## Handling Precautions

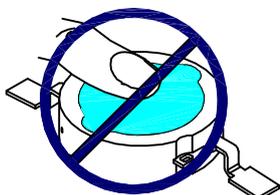
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

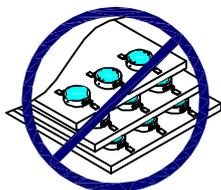
1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



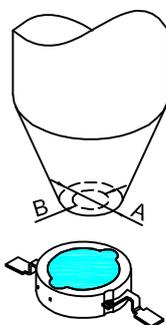
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.

- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.

- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

## Flux Characteristics at 500mA Ambient Temperature, $T_a = 25^\circ\text{C}$

Color	Part No.	Luminous Flux (lm) @ 500mA [1]			Typical Luminous Flux (lm) [1]
		Code.	Min.	Max.	Typ.
Reddish-Orange (AlGaInP)	KA-8080SE9Z1S/2	B8	35	42	45
		B9	42	50	
		B10	50	60	
Super Bright Yellow (AlGaInP)	KA-8080SY9Z1S/2	B8	35	42	45
		B9	42	50	
		B10	50	60	
Deep-Red (AlGaInP)	KA-8080SUR10Z1S/2	B3	14	17	18
		B4	17	20	
		B5	20	24	

Note:

1. Minimum luminous flux performance guaranteed within published operating conditions. Kingbright maintains tolerance of +/-15% on flux.

## Optical Characteristics at 500mA Ambient Temperature, $T_a = 25^\circ\text{C}$

Color	Dominant Wavelength [1] $\lambda_D$			Typical Spectral Halfwidth [2] (nm) $\Delta\lambda_{1/2}$	Typical Temperature Coefficient of Dominant Wavelength (nm/ $^\circ\text{C}$ ) $\Delta\lambda_D/\Delta T$	Typical Viewing Angle [3] (degrees) $2\theta_{1/2}$
	Min.	Typ.	Max.			
Reddish-Orange	619nm	623nm	629nm	22	0.03	120 $^\circ$
Super Bright Yellow	586nm	591nm	594nm	23	0.07	120 $^\circ$
Deep-Red	650nm	660nm	670nm	20	0.12	120 $^\circ$

Notes:

1. Dominant wavelength is derived from the CIE 1931 Chromaticity diagram and represents the perceived color.
2. Spectral width at 1/2 of the peak intensity.
3. Viewing angle is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.

## Electrical Characteristics at 500mA Ambient Temperature, $T_a = 25^\circ\text{C}$

Color	Forward Voltage $V_f$ [1] (V)			Typical Temperature Coefficient of Forward Voltage [2] (mV/ $^\circ\text{C}$ ) $\Delta V_f/\Delta T$	Typical Thermal Resistance ( $^\circ\text{C/W}$ ) $R_{th\ j\text{-slug}}$
	Min.	Typ.	Max.		
Reddish-Orange	2.0	2.7	3.3	-2.8	12
Super Bright Yellow	2.0	2.5	3.1	-2.6	12
Deep-Red	-	2.5	3.2	-2.5	9

Notes:

1. Kingbright maintains a tolerance of +/- 0.1V on forward voltage measurements.
2. Measured between  $25^\circ\text{C} < T_J < 110^\circ\text{C}$  at  $I_F = 500\text{ mA}$ .

## Absolute Maximum Ratings

Parameter	Reddish-Orange/Super Bright Yellow/Deep-Red
DC Forward Current (mA) [1]	500
Peak Pulsed Forward Current (mA)	700
Average Forward Current (mA)	500
Reverse Voltage (V)	5
ESD Sensitivity	8000V HBM
LED Junction Temperature (°C)	110
Operation Temperature (°C)	-40 to+ 100
Storage Temperature (°C)	-40 to+ 110
Soldering Temperature (°C)	260 For 5 Seconds

**Note:**

1. Proper current derating must be observed to maintain junction temperature below the maximum.

## Moisture Sensitivity

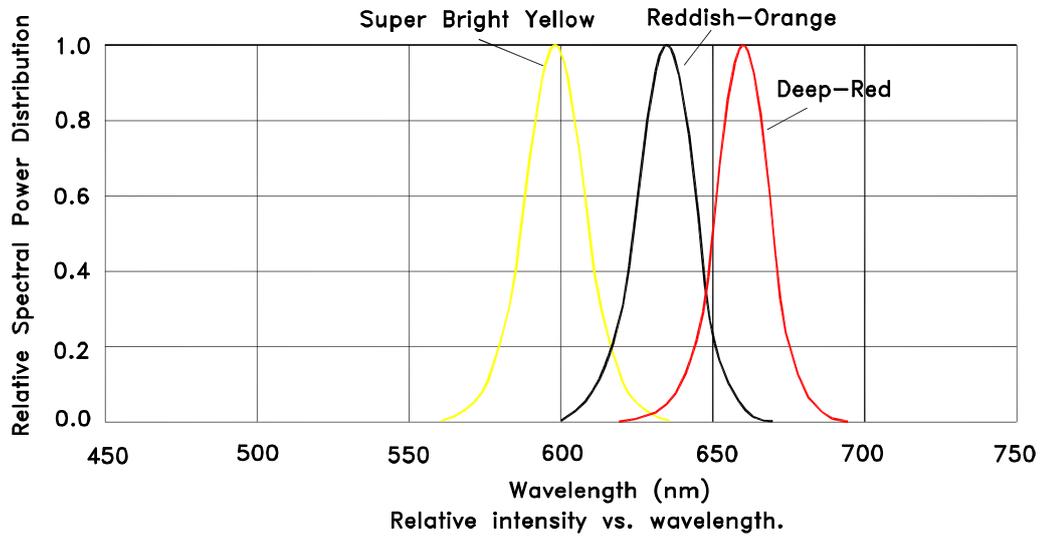
KA-8080/2 LEDs are packaged in airtight and moisture-resistant bags to prevent moisture absorption which may lead to catastrophic failure in reflow soldering process. Kingbright recommends that the devices must be baked before soldering if they are removed from the original package, and are exposed to environmental conditions for longer than the durations (unit: days) defined in the table below. Recommended baking conditions are 24 hours at 80°C.

Temperature	Maximum Percent Relative Humidity						
	30%	40%	50%	60%	70%	80%	90%
30°C	9	5	4	3	1	1	1
25°C	12	7	5	4	2	1	1
20°C	17	9	7	6	2	2	1

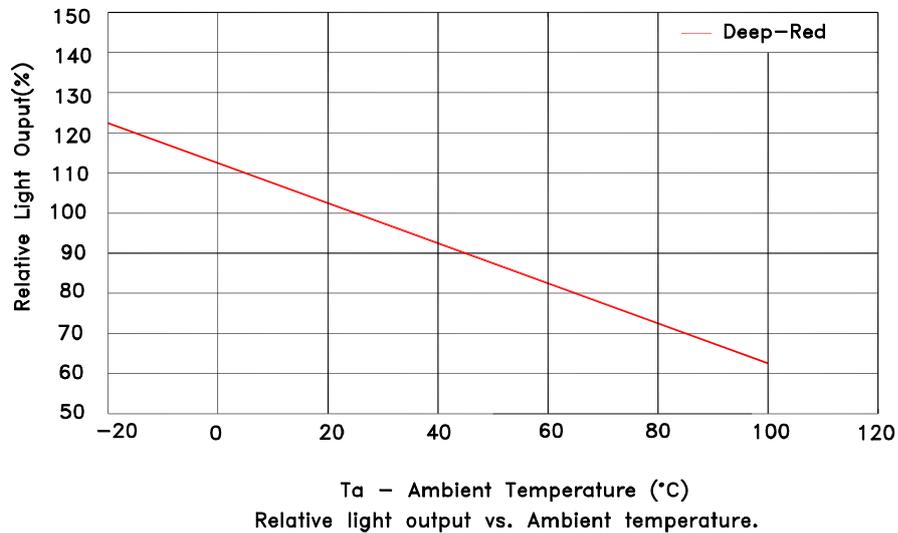
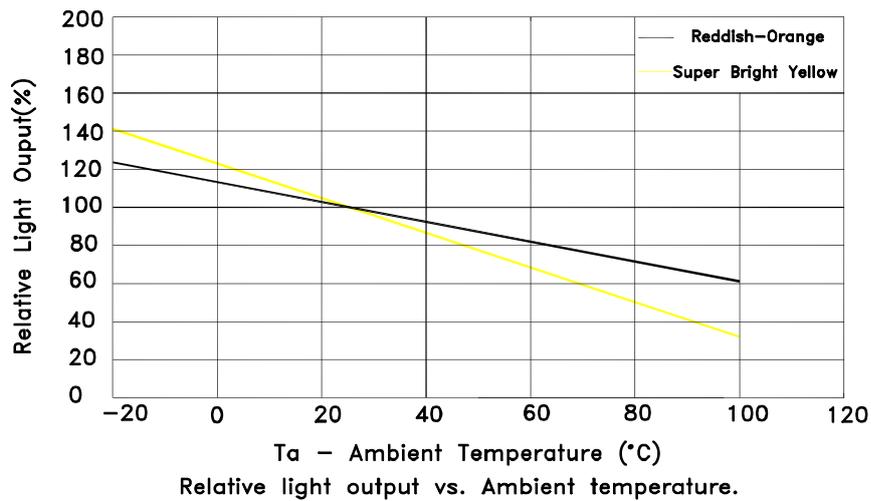
## Storage Conditions

After being removed from the original sealed package, KA-8080/2 LEDs should be stored at a temperature of 25 °C with a relative humidity lower than 10%. Under such conditions, storage duration is excluded from the exposure duration as defined in the Moisture Sensitivity section.

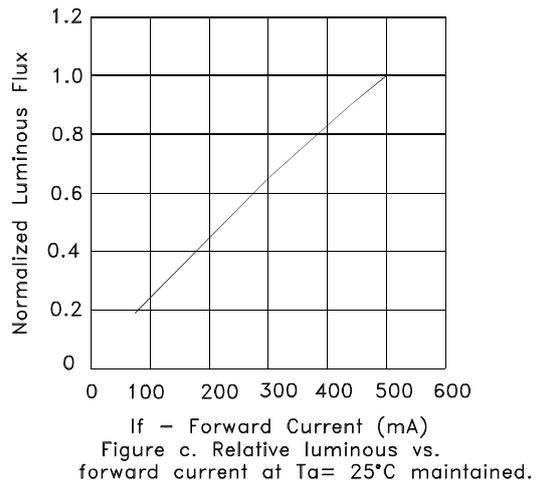
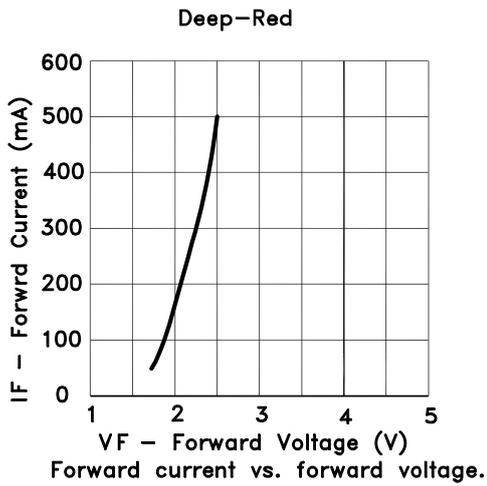
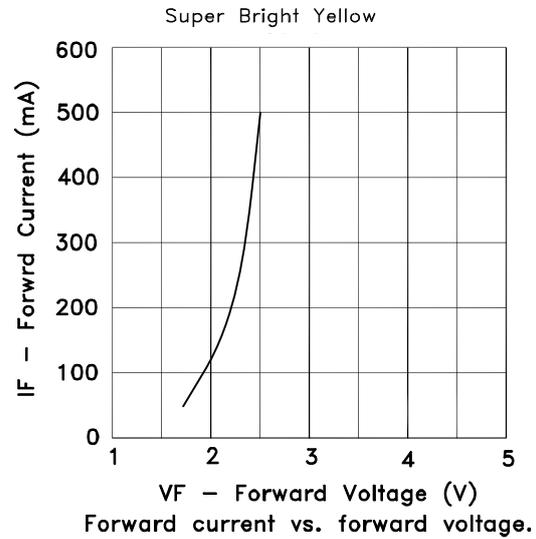
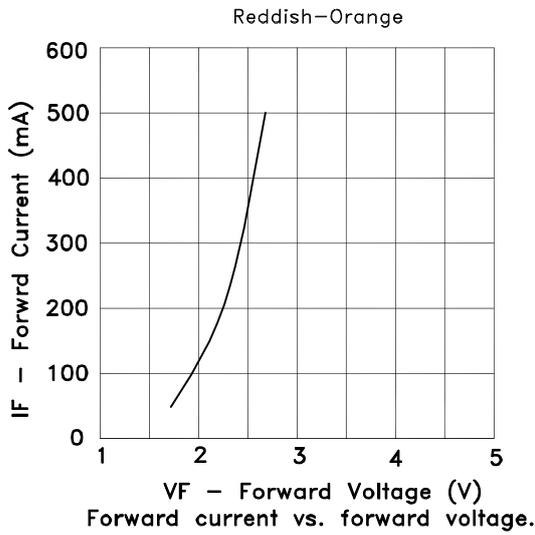
## Wavelength Characteristics $T_a = 25^\circ\text{C}$



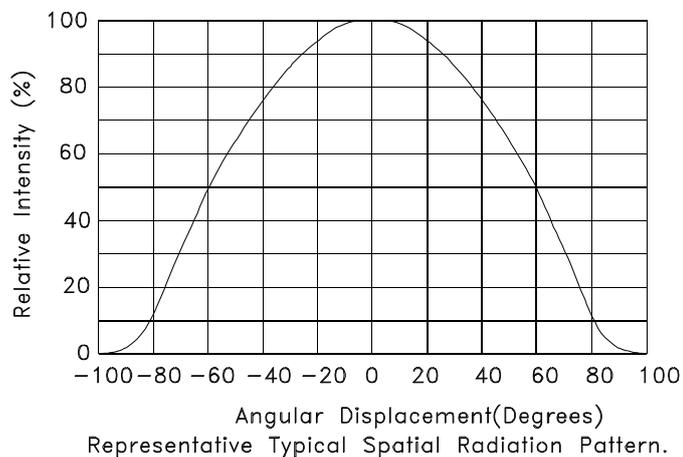
## Light Output Characteristics



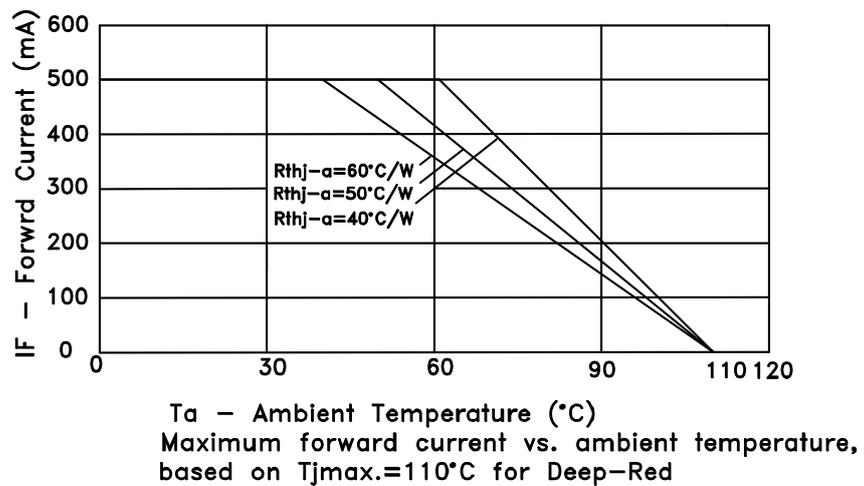
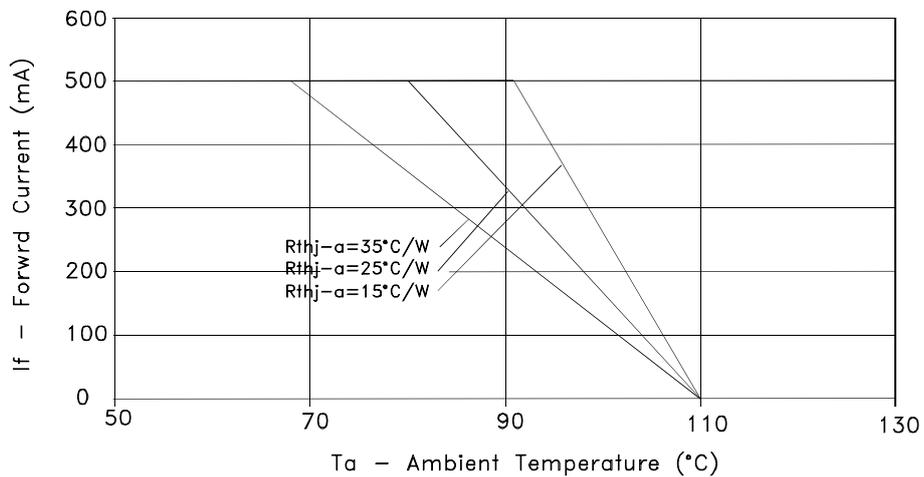
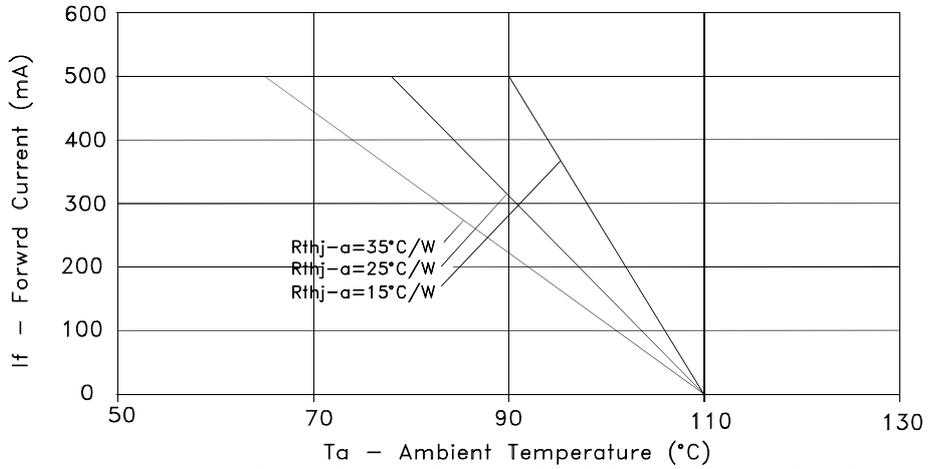
## Forward Current Characteristics, $T_a = 25^\circ\text{C}$



## Representative Typical Spatial Radiation Pattern

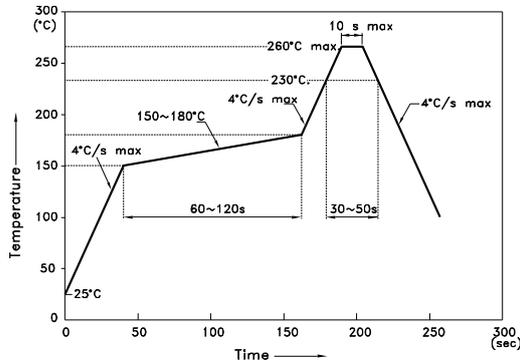


## Current Derating Curves



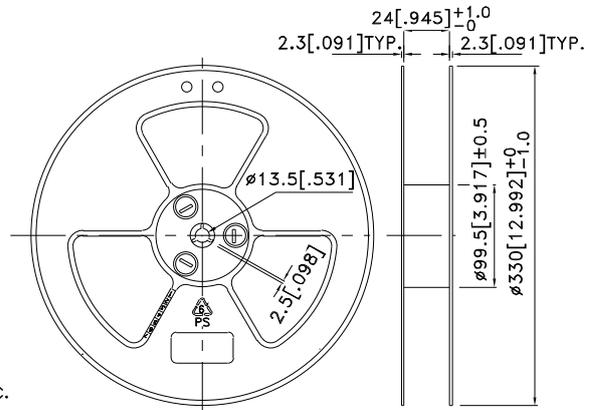
Reflow soldering is recommended and the soldering profile is shown below.  
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

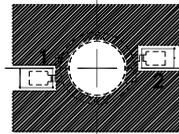
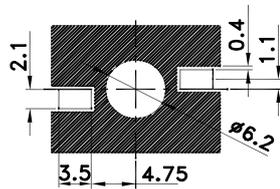


- NOTES:
1. We recommend the reflow temperature 245°C (+/-5°C). The maximum soldering temperature should be limited to 260°C.
  2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
  3. Number of reflow process shall be 2 times or less.

Reel Dimension

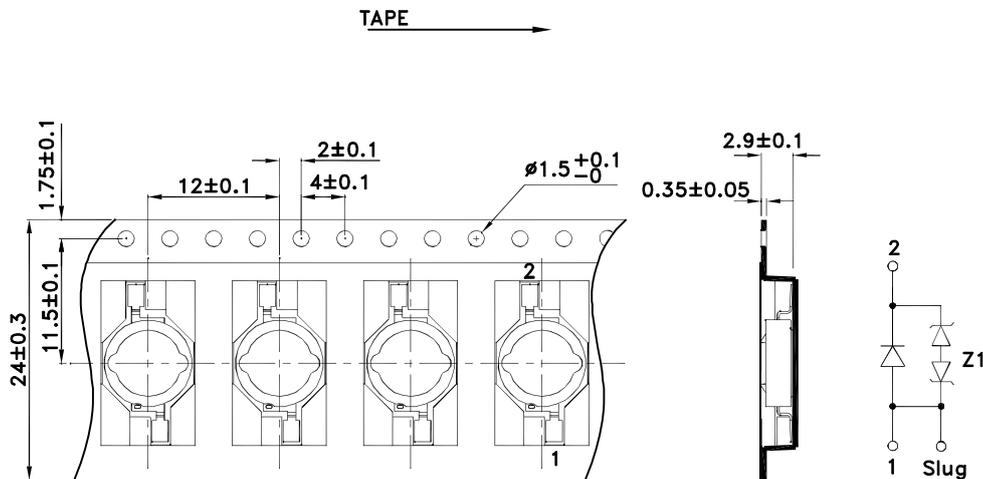


## Recommended Soldering Pattern (Units : mm ; Tolerance: $\pm 0.1$ )



Solder resist

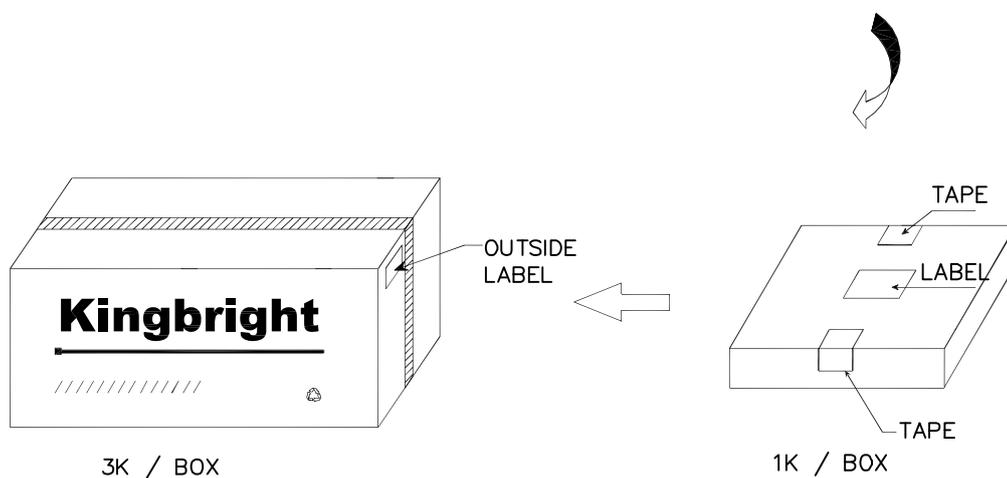
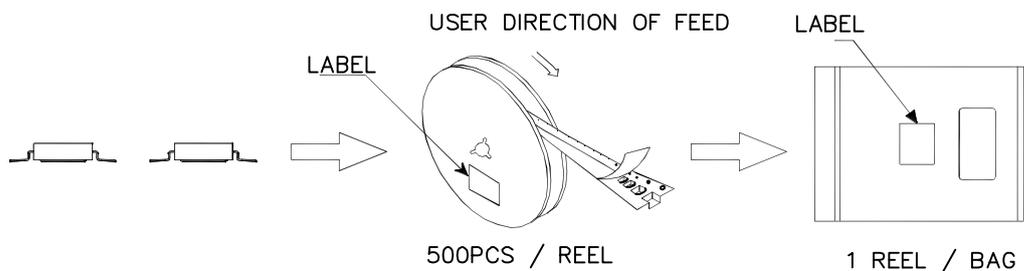
## Tape Dimensions (Units : mm)



# Kingbright

## PACKING & LABEL SPECIFICATIONS

## KA-8080/2 SERIES



<h1>Kingbright</h1>	
P/NO: KA-8080xxx	
QTY: 500 pcs	Q.C. <span style="border: 1px solid black; border-radius: 50%; padding: 2px;">Q C XX XX XXXX PASSED</span>
S/N: XXXX	
CODE: XXX	
LOT NO:	
 XXXXXXXXXXXX	
RoHS Compliant	